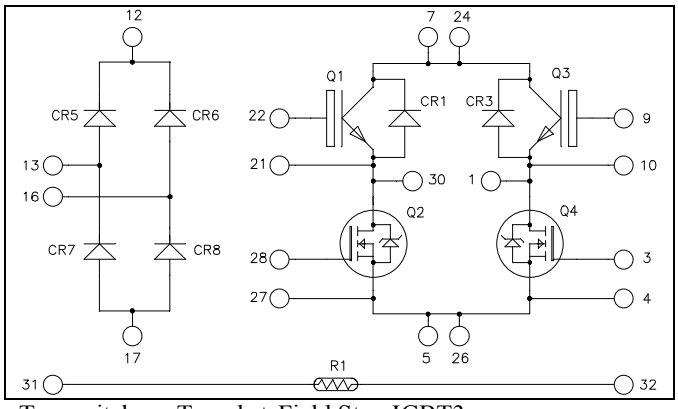
APTCV60HM45RCT3G

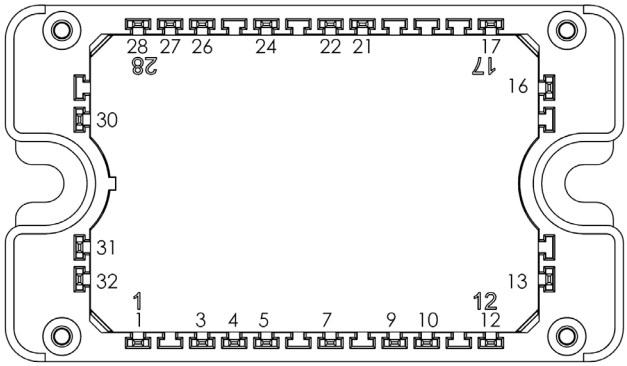
Full bridge + rectifier bridge
CoolMOS & Trench + Field Stop IGBT3
Power Module

Trench & Field Stop IGBT3 Q1, Q3:
V_{CES} = 600V ; I_C = 50A @ Tc = 80°C

CoolMOS™ Q2, Q4:
V_{DSS} = 600V
R_{DSon} = 45mΩ max @ Tj = 25°C



Top switches : Trench + Field Stop IGBT3
Bottom switches : CoolMOS™



All multiple inputs and outputs must be shorted together
7/24 ; 5/26

Application

- Solar converter

Features

- ***Q2, Q4 CoolMOS™***
  - Ultra low R_{DSon}
  - Low Miller capacitance
  - Ultra low gate charge
  - Avalanche energy rated
- ***Q1, Q3 Trench & Field Stop IGBT3***
  - Low voltage drop
  - Switching frequency up to 20 kHz
  - RBSOA & SCSOA rated
  - Low tail current
- ***SiC Schottky Diode (CR1, CR3)***
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
- Very low stray inductance
- Kelvin source for easy drive
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Optimized conduction & switching losses
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Easy paralleling due to positive T_C of V_{CEsat}
- RoHS Compliant

All ratings @ T_j = 25°C unless otherwise specified

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

1. Top switches

1.1 Top Trench + Field Stop IGBT3 characteristics (per IGBT)

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{CES}	Zero Gate Voltage Collector Current	V_{GE} = 0V, V_{CE} = 600V				250	µA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	V_{GE} =15V I_C = 50A	T_j = 25°C		1.5	1.9	V
			T_j = 150°C		1.7		
$V_{GE(th)}$	Gate Threshold Voltage	V_{GE} = V_{CE} , I_C = 600µA		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	V_{GE} = 20V, V_{CE} = 0V				600	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
C_{ies}	Input Capacitance	V_{GE} = 0V V_{CE} = 25V f = 1MHz			3150		pF
C_{oes}	Output Capacitance				200		
C_{res}	Reverse Transfer Capacitance				95		
Q_G	Gate charge	V_{GE}=±15V, I_C=50A V_{CE}=300V			0.5		µC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) V_{GE} = ±15V V_{Bus} = 300V I_C = 50A R_G = 8.2Ω			110		ns
T_r	Rise Time				45		
$T_{d(off)}$	Turn-off Delay Time				200		
T_f	Fall Time				40		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (150°C) V_{GE} = ±15V V_{Bus} = 300V I_C = 50A R_G = 8.2Ω			120		ns
T_r	Rise Time				50		
$T_{d(off)}$	Turn-off Delay Time				250		
T_f	Fall Time				60		
E_{off}	Turn-off Switching Energy	V_{GE} = ±15V V_{Bus} = 300V I_C = 50A R_G = 8.2Ω	T_j = 25°C		1.35		mJ
			T_j = 150°C		1.75		
I_{sc}	Short Circuit data	V_{GE} ≤15V ; V_{Bus} = 360V t_p ≤ 6µs ; T_j = 150°C			250		A
R_{thJC}	Junction to Case Thermal resistance					0.85	°C/W

1.2 Top SiC diode characteristics (CR1, CR3) (per diode)

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I_{RM}	Maximum Reverse Leakage Current	V_R=600V	T_j = 25°C		20	120	µA
			T_j = 175°C		40	600	
I_F	DC Forward Current		Tc = 100°C		20		A
V_F	Diode Forward Voltage	I_F = 20A	T_j = 25°C		1.6	1.8	V
			T_j = 175°C		2	2.4	
Q_C	Total Capacitive Charge	I_F = 20A, V_R = 300V di/dt = 800A/µs			28		nC
C	Total Capacitance	f = 1MHz, V_R = 200V			130		pF
		f = 1MHz, V_R = 400V			100		
R_{thJC}	Junction to Case Thermal resistance					1.5	°C/W

2. Bottom switches

2.1 Bottom CoolMOS™ characteristics (Per CoolMOS™)

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		600	V
I_D	Continuous Drain Current	T_c = 25°C	49	A
		T_c = 80°C	38	
I_{DM}	Pulsed Drain current		130	
V_{GS}	Gate - Source Voltage		±20	V
R_{DSon}	Drain - Source ON Resistance		45	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	250	W
I_{AR}	Avalanche current (repetitive and non repetitive)		15	A
E_{AR}	Repetitive Avalanche Energy		3	mJ
E_{AS}	Single Pulse Avalanche Energy		1900	

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V,V_{DS} = 600V	T_j = 25°C			250	µA
		V_{GS} = 0V,V_{DS} = 600V	T_j = 125°C			500	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 24.5A			40	45	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 3mA		2.1	3	3.9	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0V				100	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	V_{GS} = 0V ; V_{DS} = 25V f = 1MHz		7.2		nF
C_{oss}	Output Capacitance			8.5		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 300V I_D = 49A		150		nC
Q_{gs}	Gate – Source Charge			34		
Q_{gd}	Gate – Drain Charge			51		
$T_{d(on)}$	Turn-on Delay Time	**Inductive Switching (125°C)** V_{GS} = 10V V_{Bus} = 400V I_D = 49A R_G = 5Ω		21		ns
T_r	Rise Time			30		
$T_{d(off)}$	Turn-off Delay Time			100		
T_f	Fall Time			45		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 25°C** V_{GS} = 10V ; V_{Bus} = 400V I_D = 49A ; R_G = 5Ω		405		µJ
E_{off}	Turn-off Switching Energy			520		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 125°C** V_{GS} = 10V ; V_{Bus} = 400V I_D = 49A ; R_G = 5Ω		658		µJ
E_{off}	Turn-off Switching Energy			635		
R_{thJC}	Junction to Case Thermal resistance				0.5	°C/W

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current (Body diode)		Tc = 25°C		49		A
			Tc = 80°C		38		
V_{SD}	Diode Forward Voltage	V_{GS} = 0V, I_S = - 49A				1.2	V
dv/dt	Peak Diode Recovery ❶					4	V/ns
t_{rr}	Reverse Recovery Time	I_S = - 49A V_R = 350V di_S/dt = 100A/µs	T_j = 25°C		600		ns
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		17		µC

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.
$I_S \le$ - 49A di/dt ≤ 100A/µs $V_R \le V_{DSS}$ $T_j \le$ 150°C

3. Rectifier bridge (per diode)

Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit
V_R	Maximum DC reverse Voltage			600	V
V_{RRM}	Maximum Peak Repetitive Reverse Voltage				
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	T_C = 80°C	40	A
I_{FSM}	Non-Repetitive Forward Surge Current	8.3ms	T_J = 45°C	320	

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_F	Diode Forward Voltage	I_F = 30A			1.8	2.2	V
		I_F = 60A			2.2		
		I_F = 30A	T_j = 125°C		1.5		
I_{RM}	Maximum Reverse Leakage Current	V_R = 600V	T_j = 25°C			250	µA
			T_j = 125°C			500	

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t_{rr}	Reverse Recovery Time	I_F=1A,V_R=30V di/dt = 100A/µs	T_j = 25°C		22		ns
t_{rr}	Reverse Recovery Time	I_F = 30A V_R = 400V di/dt = 200A/µs	T_j = 25°C		25		ns
			T_j = 125°C		160		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		35		nC
			T_j = 125°C		480		
I_{RRM}	Reverse Recovery Current		T_j = 25°C		3		A
			T_j = 125°C		6		
t_{rr}	Reverse Recovery Time	I_F = 30A V_R = 400V di/dt = 1000A/µs	T_j = 125°C		85		ns
Q_{rr}	Reverse Recovery Charge				920		µC
I_{RRM}	Reverse Recovery Current				20		A
R_{thJC}	Junction to Case Thermal Resistance					1.2	°C/W

4. Thermal and package characteristics

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic		Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C			50		kΩ
$\Delta R_{25}/R_{25}$				5		%
$B_{25/85}$	T_{25} = 298.15 K			3952		K
ΔB/B		T_C=100°C		4		%

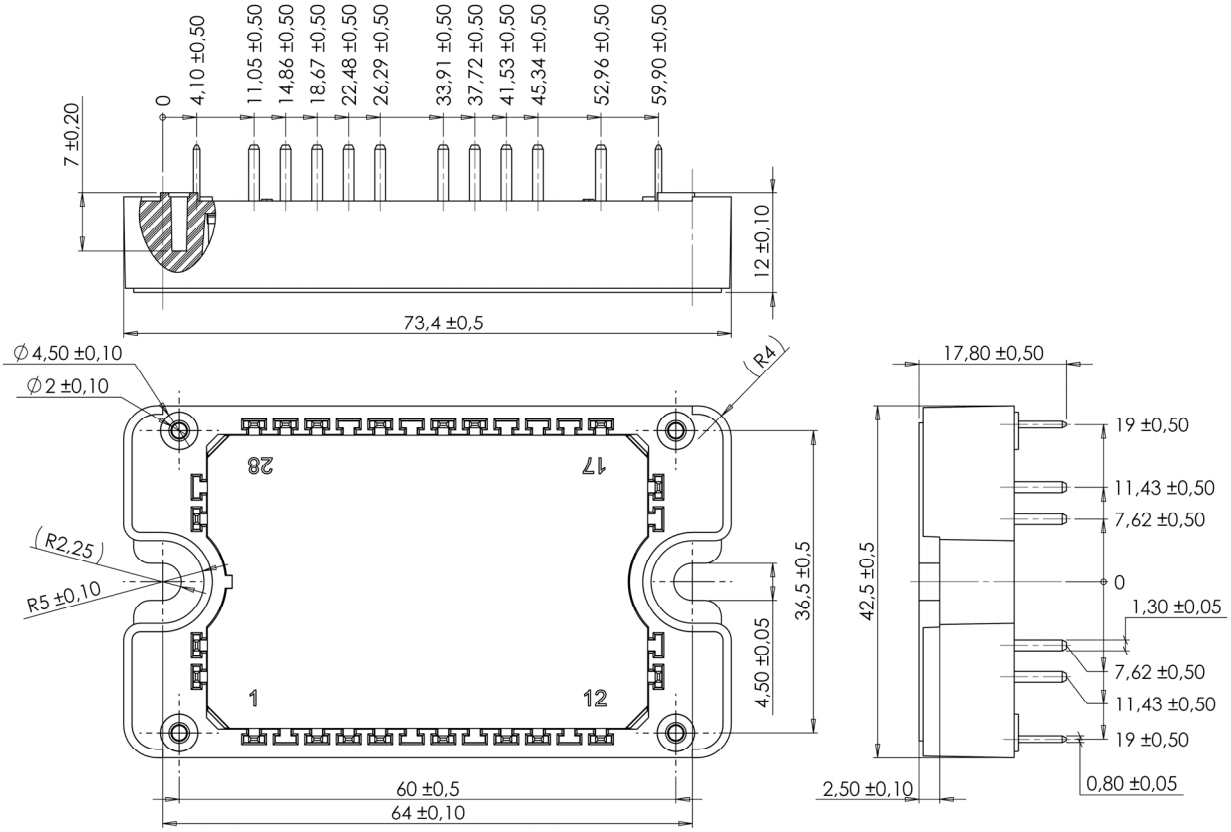
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature
R_T: Thermistor value at T

Package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		175	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M4	2		3	N.m
Wt	Package Weight					110	g

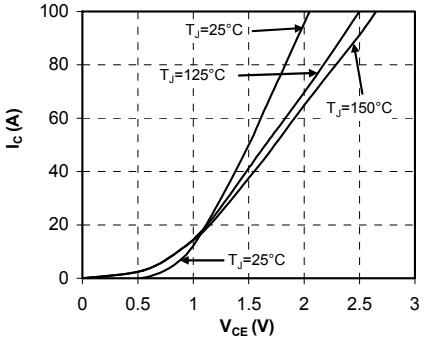
SP3 Package outline (dimensions in mm)



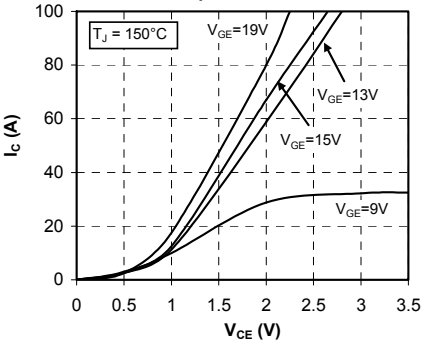
5. Top switches curves

5.1 Top Trench + Field Stop IGBT3 typical performance curves (per IGBT)

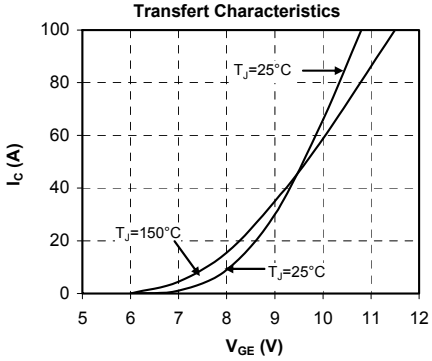
Output Characteristics (V_{GE}=15V)



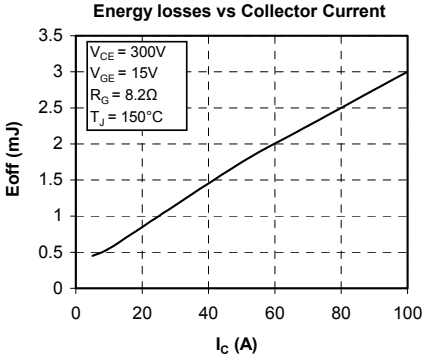
Output Characteristics



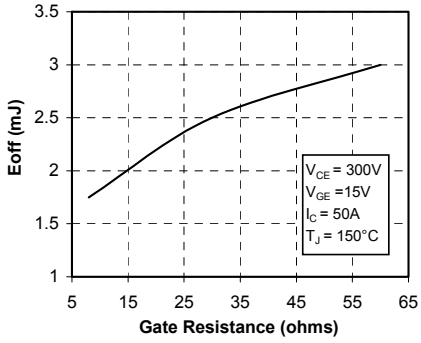
Transfert Characteristics



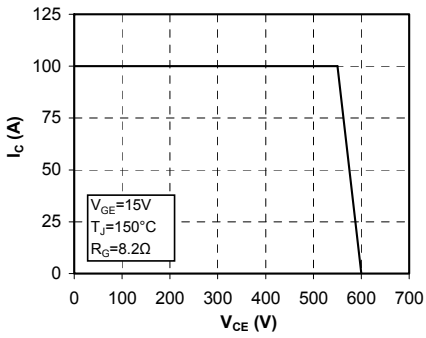
Energy losses vs Collector Current



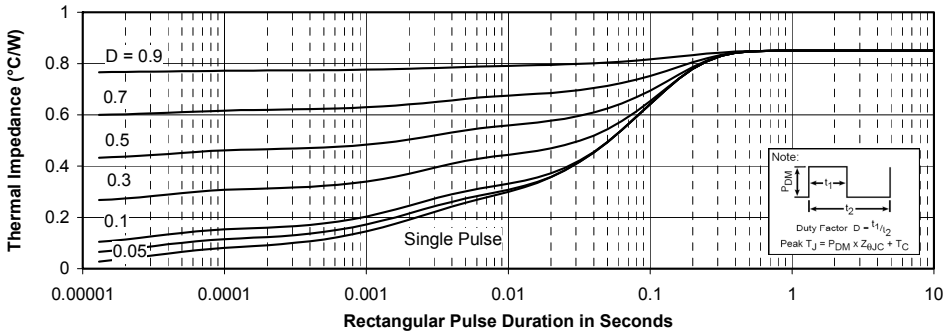
Switching Energy Losses vs Gate Resistance



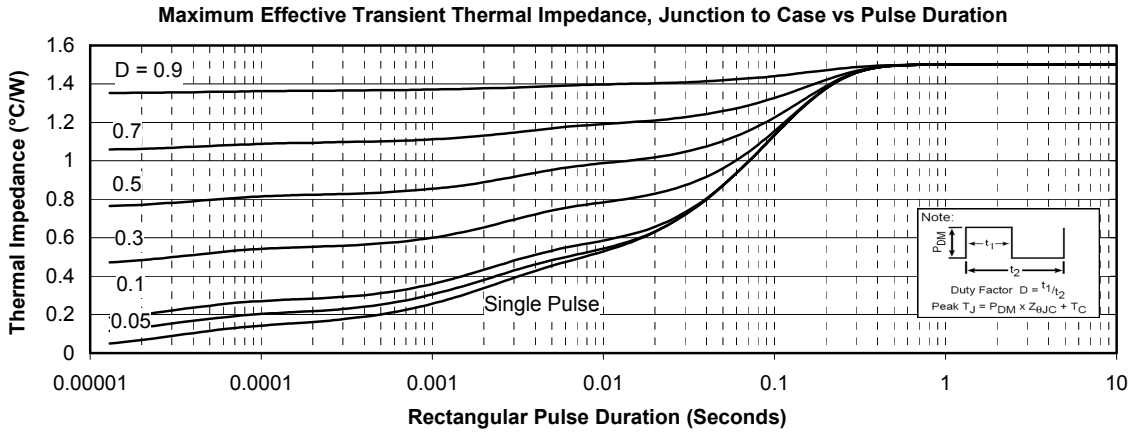
Reverse Bias Safe Operating Area

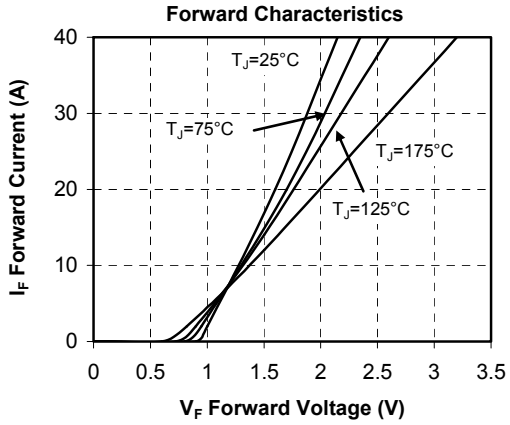


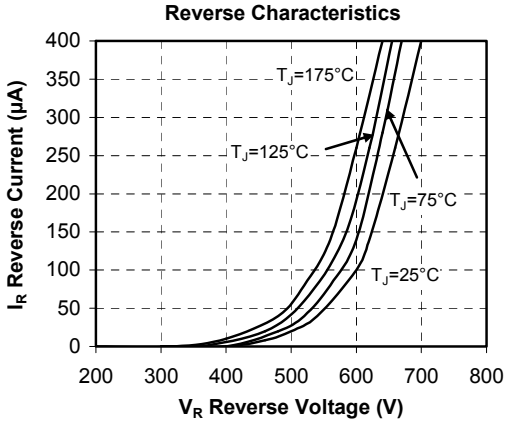
maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration

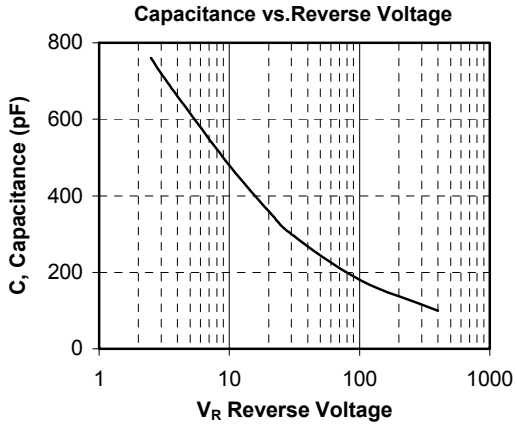


5.2 Top SiC diode characteristics (per diode)

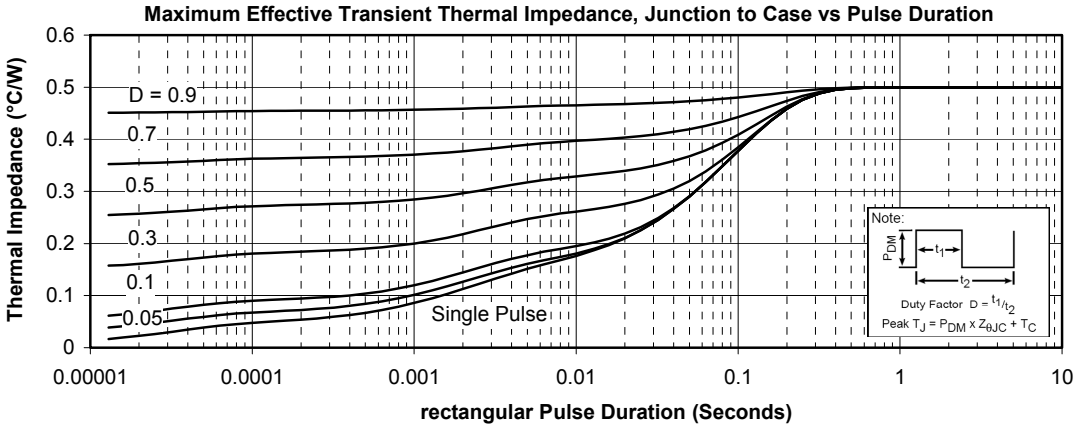


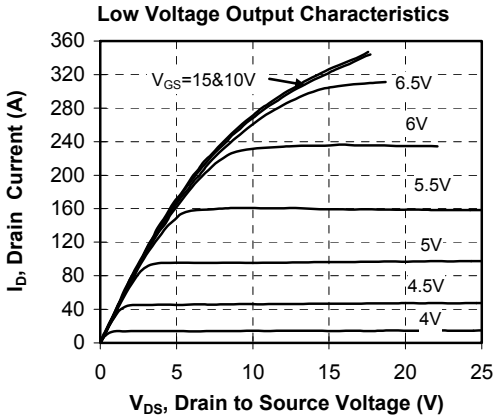


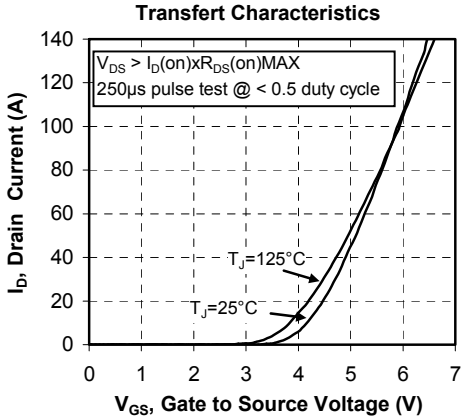


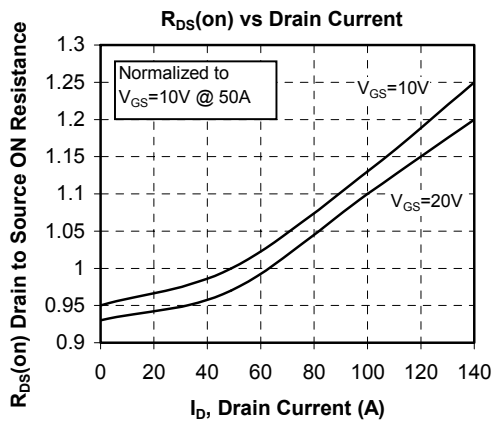


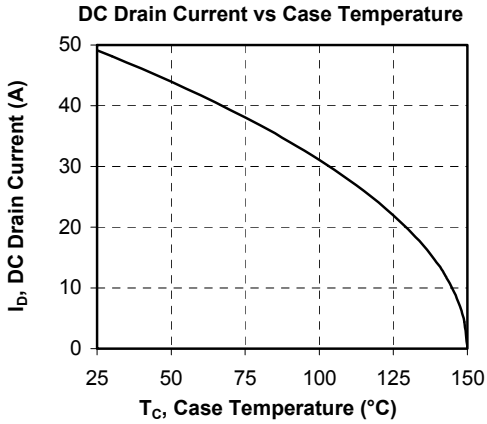
6. Bottom switches curves (per CoolMOS™)



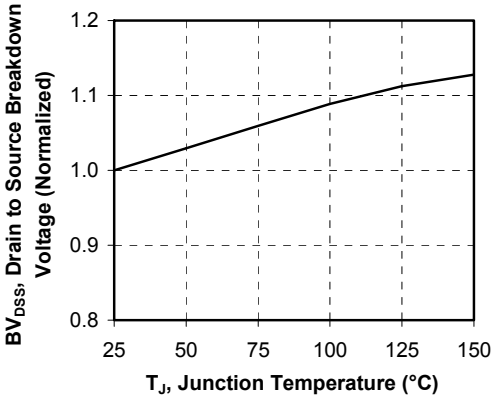




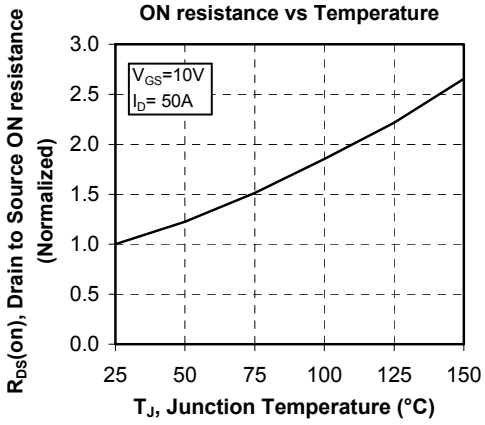




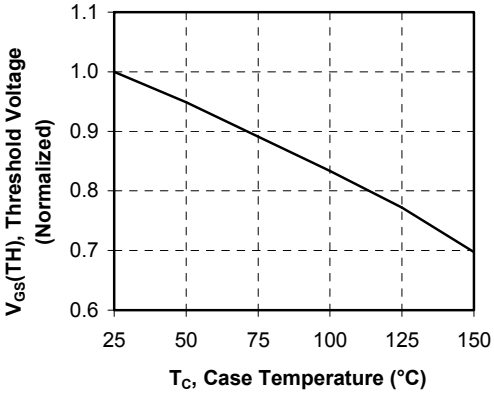
Breakdown Voltage vs Temperature



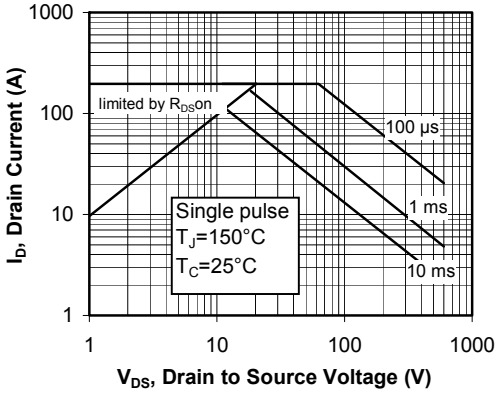
ON resistance vs Temperature



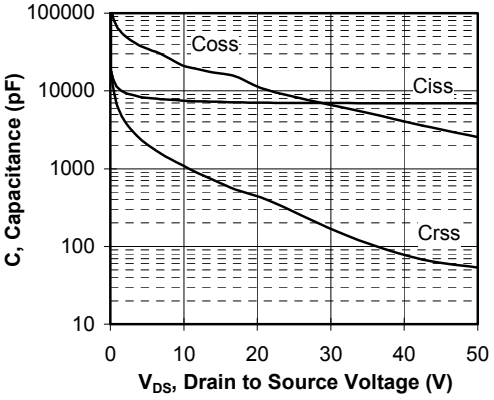
Threshold Voltage vs Temperature



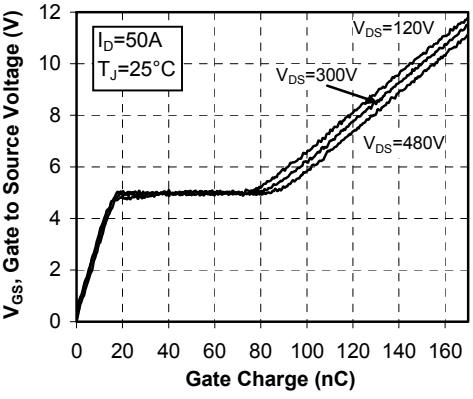
Maximum Safe Operating Area



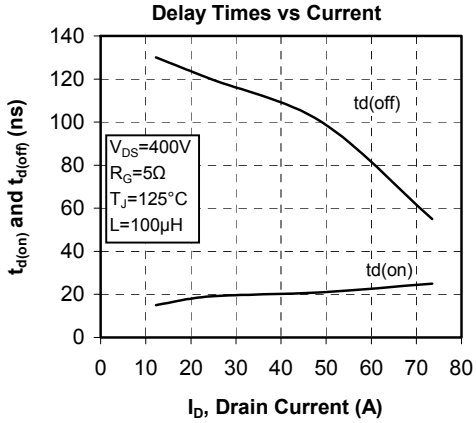
Capacitance vs Drain to Source Voltage



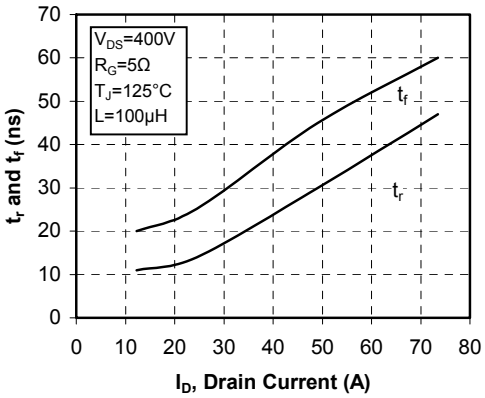
Gate Charge vs Gate to Source Voltage



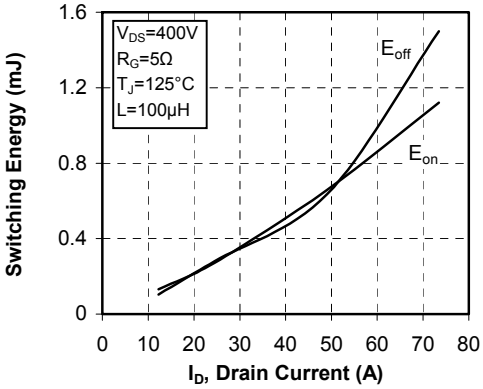
Delay Times vs Current



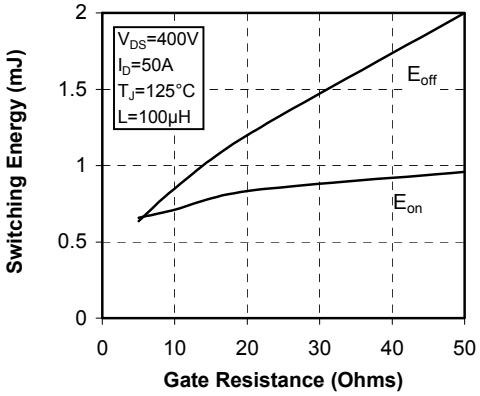
Rise and Fall times vs Current



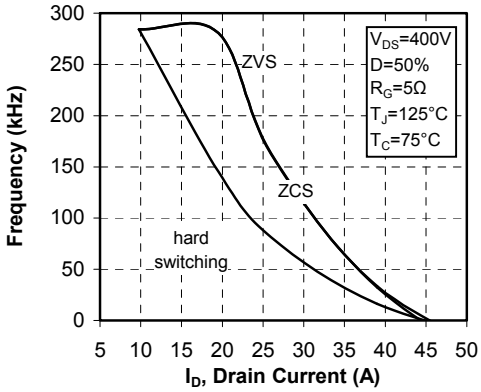
Switching Energy vs Current



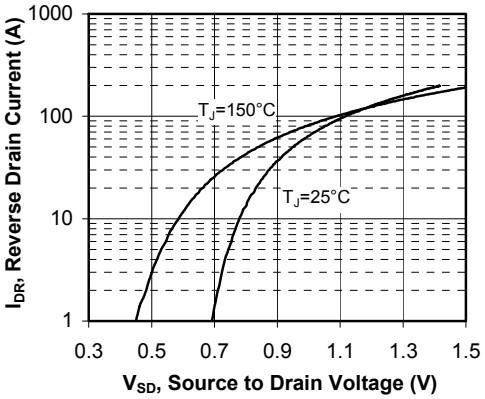
Switching Energy vs Gate Resistance



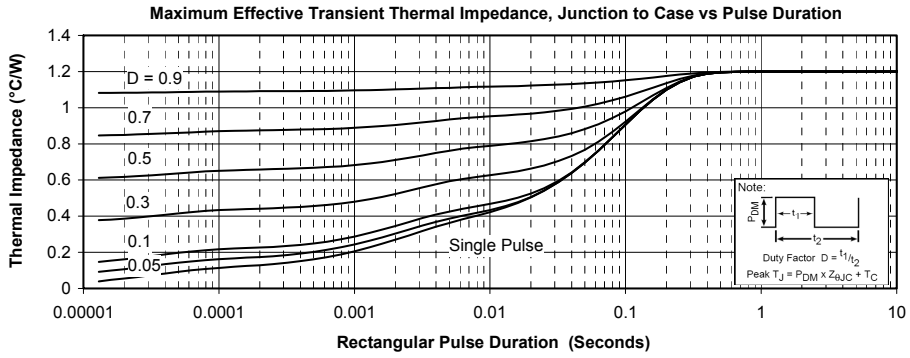
Operating Frequency vs Drain Current

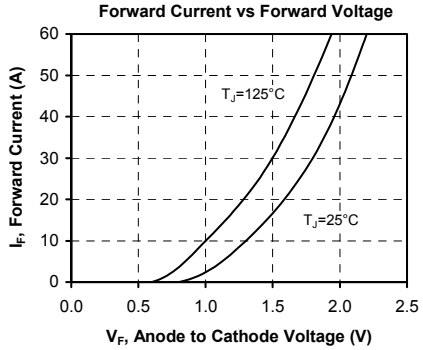


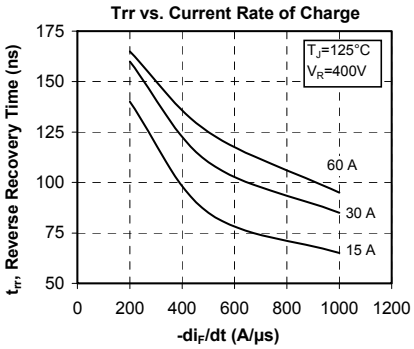
Source to Drain Diode Forward Voltage

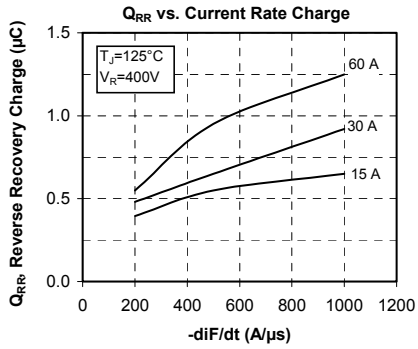


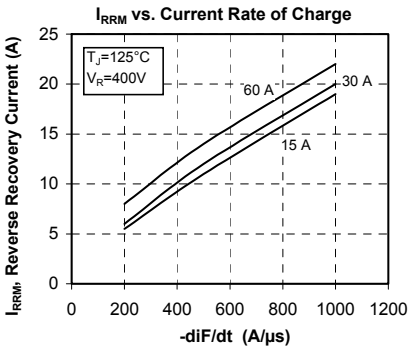
7. Typical rectifier bridge Performance Curve (per diode)

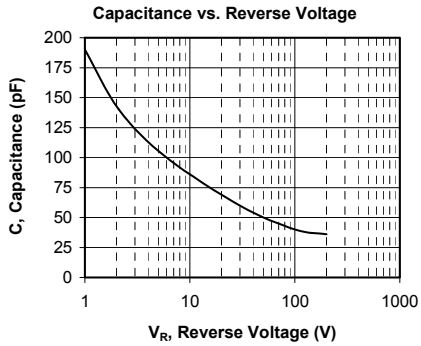












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